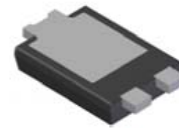


Top View



Bottom View

DO277 Rectifier

Material Content Declaration					
Material name	Substance name, e.g. Copper (Cu), Gold (Au)	CAS no., if known	Substance mass (mg)	% OF Weight (%)	ppm Of Total Weight
Lead Wire 55.87%	Copper (Cu)	7440-50-8	47.9899	99.9789	558,690.7
	Phosphorus (P)	7723-14-0	0.0005	0.0010	5.5
	Arsenic (As)	7440-38-2	0.0005	0.0010	5.5
	Tin (Sn)	7440-31-5	0.0005	0.0010	5.5
	Oxygen (O)	7782-44-7	0.0002	0.0005	2.8
	Sulfur (S)	7704-34-9	0.0058	0.0120	66.9
	Iron (Fe)	7439-89-6	0.0003	0.0007	3.7
	Nickel (Ni)	7440-02-0	0.0001	0.0003	1.7
	Bismuth (Bi)	7440-69-9	0.0009	0.0020	11.0
	Antimony (Sb)	1309-64-4	0.0009	0.0020	11.0
	Lead (Pb)	7439-92-1	0.0002	0.0005	2.8
	Zinc (Zn)	7440-66-6	0.0001	0.0003	1.7
	Total		48.00		
Solder Wafer 3.24%	Lead (Pb)	7439-92-1	2.590	93.60	30,152.4
	Tin (Sn)	7440-31-5	0.112	4.05	1303.9
	Silver (Ag)	7440-22-4	0.065	2.35	756.7
		Total		2.77	
Chip 3.76%	Silicon (Si)	7440-21-3	3.23	100.00	37,603.2
		Total		3.23	
Molding 36.09%	Silica (SiO ₂)	14808-60-7	22.97	74.11	267,461.0
	Epoxy resin	29690-82-2	5.27	17.00	61,352.6
	Phenolic resin	9003-35-4	2.73	8.80	31,759.0
	Phosphorus(P)	7723-14-0	0.01	0.05	166.0
	Carbon Black	1333-86-4	0.01	0.04	144.4
		Total		31.00	
Plating 1.04%	Tin (Sn)	7440-31-5	0.9	100.00	10,477.7
		Total		0.90	
	Total mass (mg)		85.90		